

JET-DISPENSED STRESS RELIEF LAYER IN CONTACT ARRAYS,
AND PROCESSES OF MAKING SAME

5

ABSTRACT OF THE DISCLOSURE

A stress-relief layer is formed by dispensing a polymer upon a substrate lower surface under conditions to partially embed a solder bump that is disposed upon the lower surface. The stress-relief layer flows against the solder bump. An article that exhibits a stress-relief layer with a structure characteristic of the manner of dispensing is also included. A computing system that includes a stress-relief layer with a structure characteristic of the manner of dispensing is also included.

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